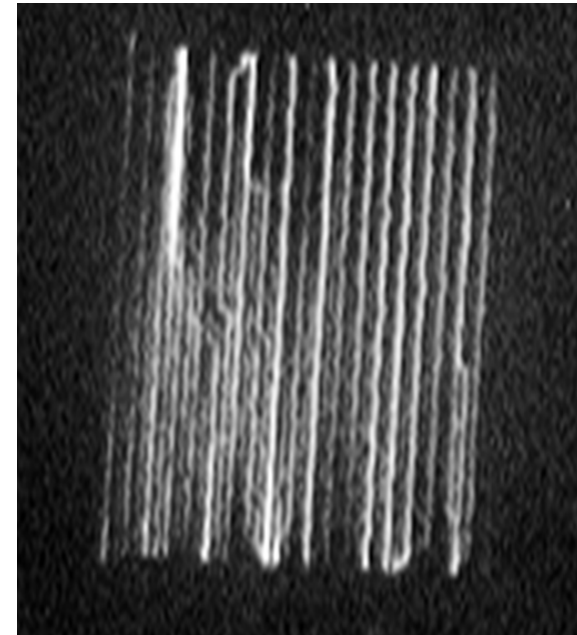
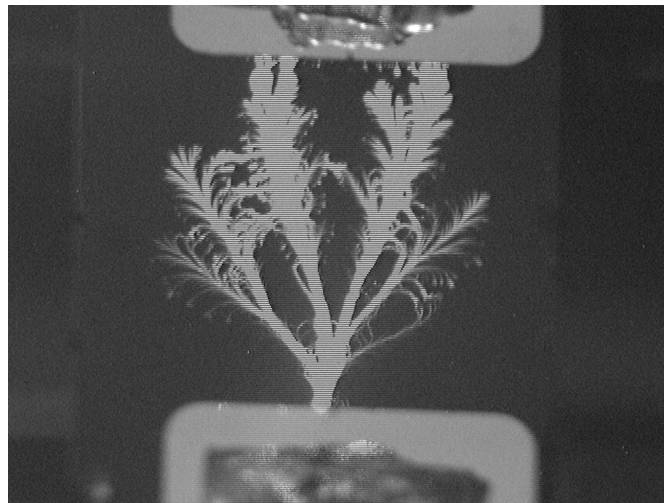
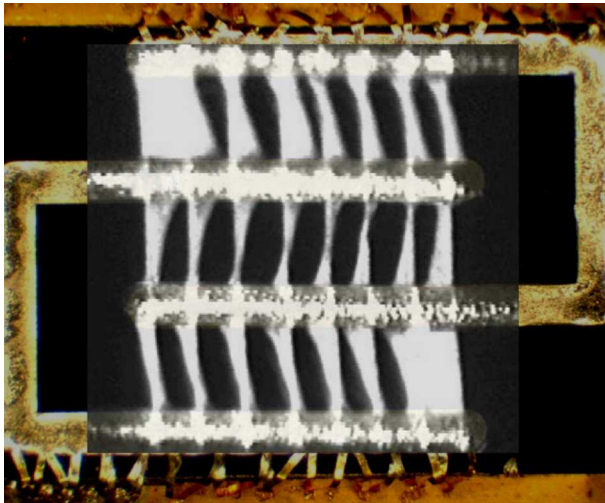


*Exceptional service in the national interest*



# MULTI-FILAMENT PCSS MODULES TO REPLACE HIGH CURRENT PULSED POWER SWITCHES

*Fred J. Zutavern, Alan Mar, G. Allen Vawter, Steven F. Glover,  
Harold P. Hjalmarson, and Kenneth H. Greives*

# High Voltage GaAs PCSS

## *Properties of high gain PCSS :*

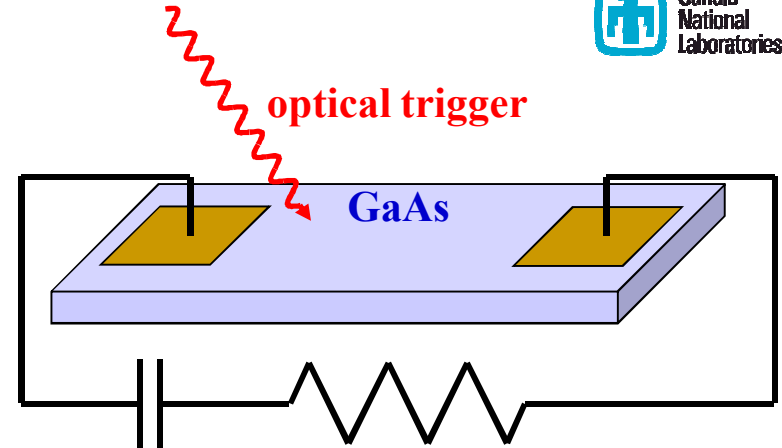
### (1) **Low Energy Triggering**

Avalanche carrier generation produces up to 100,000 e/h per photon depending on the circuit

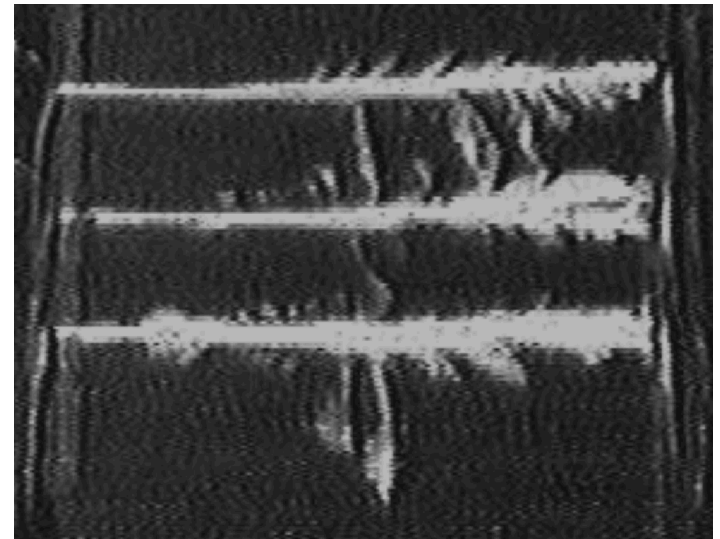
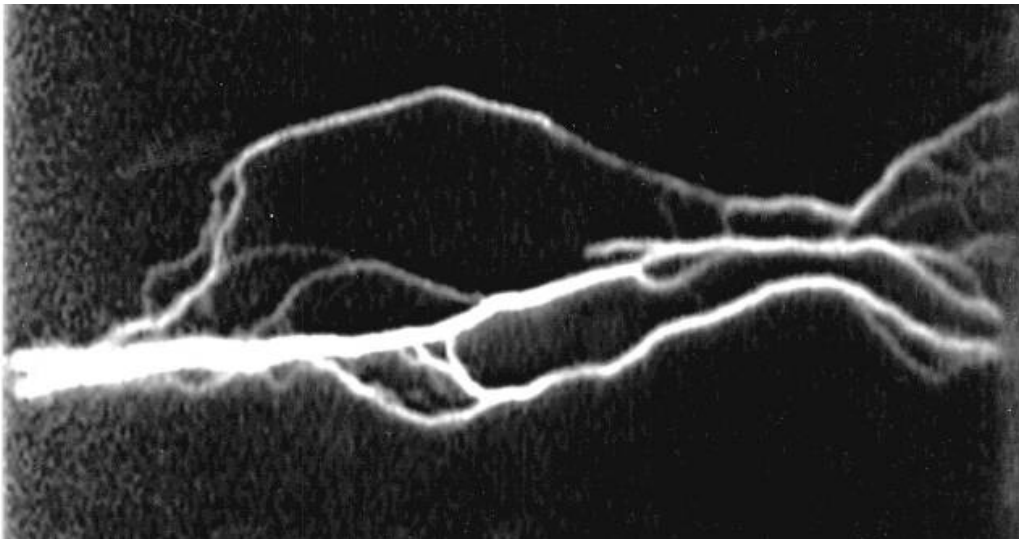
### (2) **Current Forms in Filaments**

20 A /filament  $\rightarrow$  100,000,000 shot lifetime

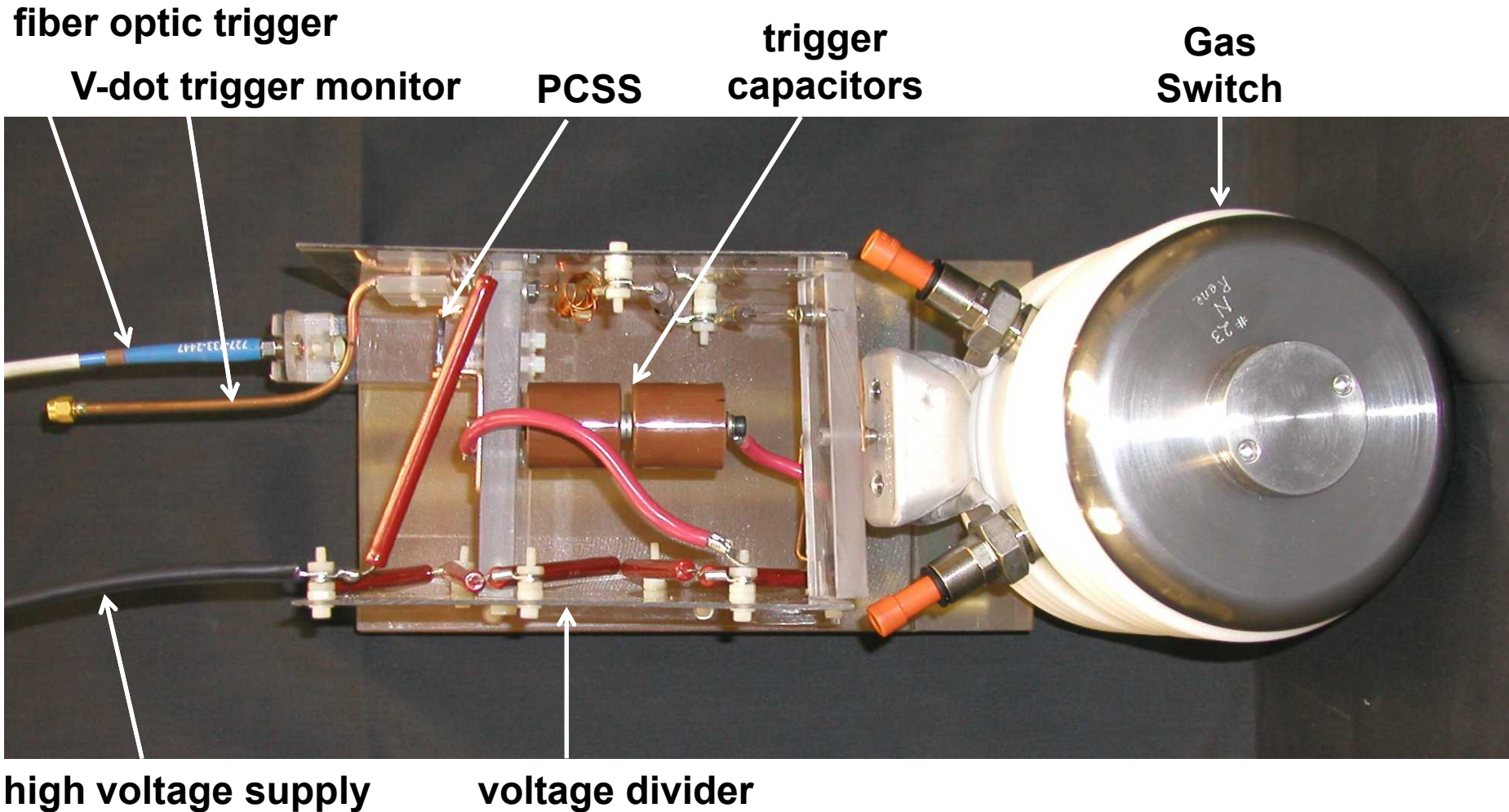
2 kA /filament  $\rightarrow$  1 shot lifetime



**220 kV, 6 kA**  
**370 ps risetime,**  
**100 ps jitter**



# PCSS Trigger for an LTD Module



# Optical Delivery Systems

## I. Single (large) laser creating lines of light

### A. Line-of-sight optics – clear, stable, straight path

Uniform, parallel beam that can focus to a point

#### 1. Discrete cylindrical lenses (glass rods)

#### 2. Cylindrical lens array ←

#### 3. Diffractive optics – extinction ratio, uniformity, many devices

a) Multiple order diffraction grating for monochromatic beam

b) Spectrum of wide-band ultra-short pulse beam

#### 4. Faceted Mirrors and beam splitters

### B. Fiber optics – maintain brightness with narrow lines

#### 1. Single mode – packing fraction

#### 2. Multi-mode – brightness and spot size

#### 3. Convert from spots to lines or dashed lines

a) Mini cylindrical lenses

b) Tapered fibers

c) Edge-emitting fibers

## II. Multiple lasers

A. One laser per bank – laser synchronization

B. One laser per filament

### 1. Edge-emitting lasers – uniformity and alignment

Photo-carrier density:  $10^{18} \text{ (cm}^{-3}\text{)}$

Trigger Laser Intensity:  $80 \text{ kW (cm}^{-2}\text{)}$

$100 \text{ nJ / 5 ns / (10 \times 2500 \mu\text{J})}$

### 2. VCSELS – linear VCSELS lase non-uniformly

C. Many lasers per filament - Fiber lasers – synchronization ←

#### 1. VCSELS – energy per laser

2. Fiber lasers – synchronization & cost

## III. Patterned substrates with uniform illumination from a single large laser or fiber bundle

A. Masks to block the light between the desired locations ←

B. Doped/implanted low mobility regions to limit filament growth  
between the desired locations

C. Etched troughs (ridges and valleys) ←

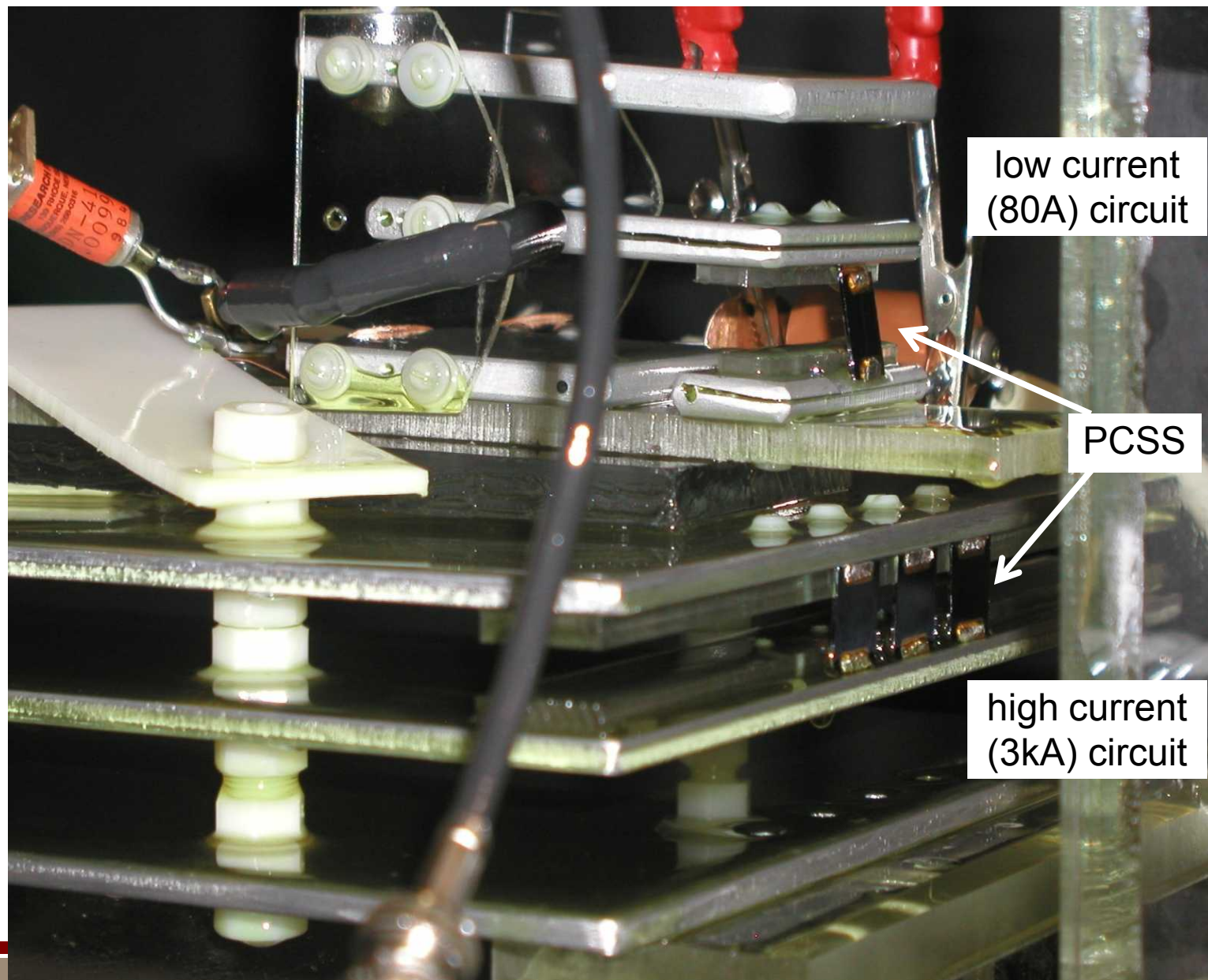
D. Issues

1. Lost light between filaments

2. Depth of the process is small compared to filament diameters

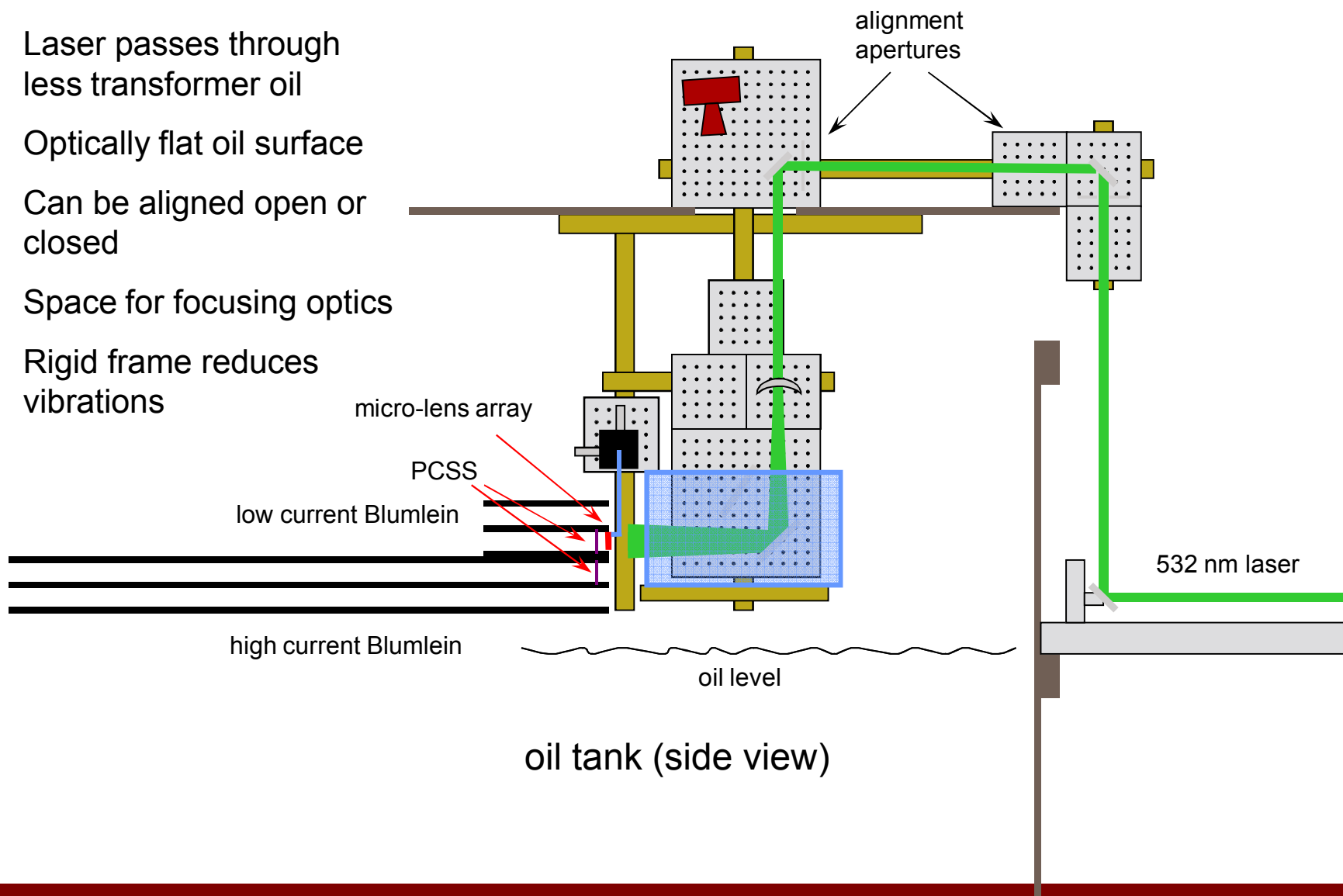


# High Current Multiple Filament Testing



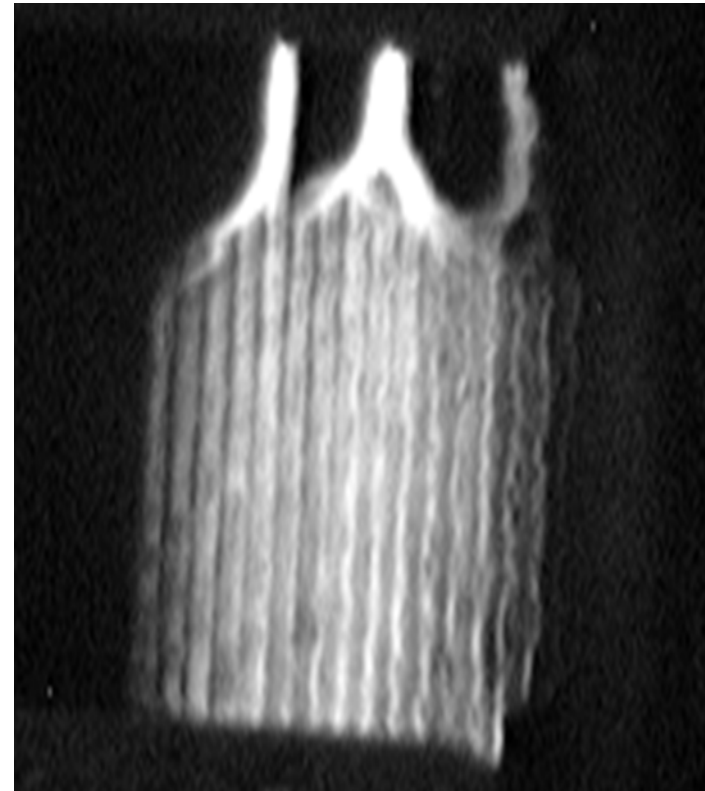
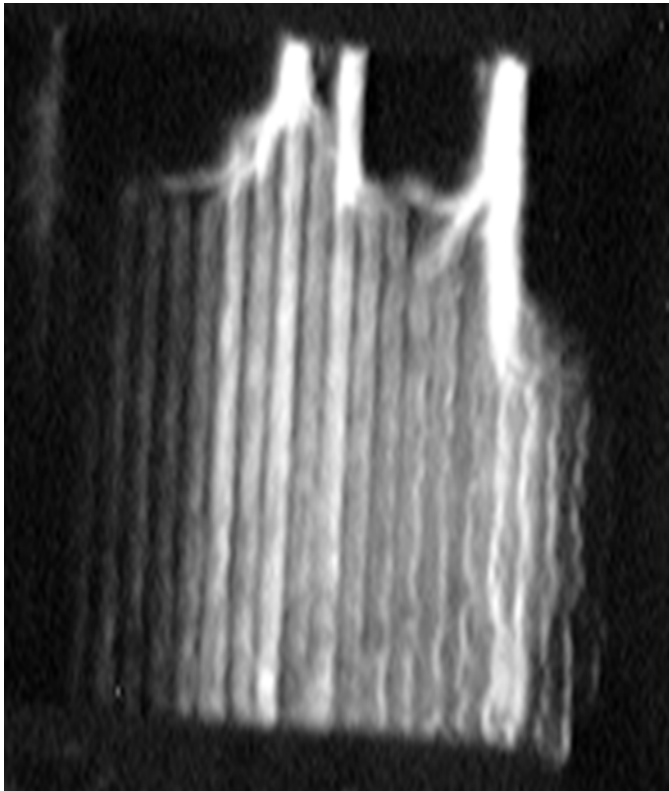
# High Current, Multi-Filament, Optical Delivery Path

- Laser passes through less transformer oil
- Optically flat oil surface
- Can be aligned open or closed
- Space for focusing optics
- Rigid frame reduces vibrations



# Multi-Filament Tests with Micro-Lens Arrays

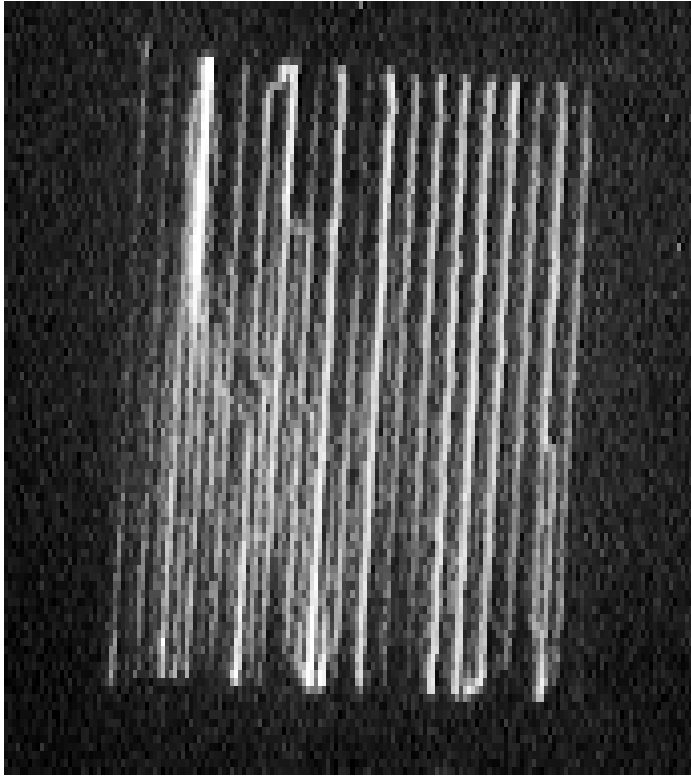
2 stacked micro-lens arrays (shorter focal length)



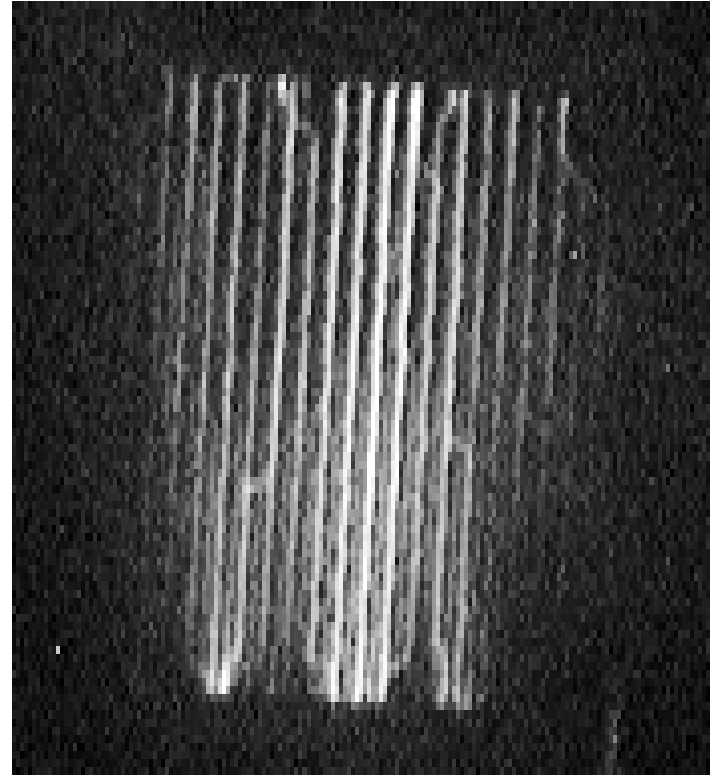


# Multi-Filament Tests with Micro-Lens Arrays

2 stacked micro-lens arrays (better alignment)



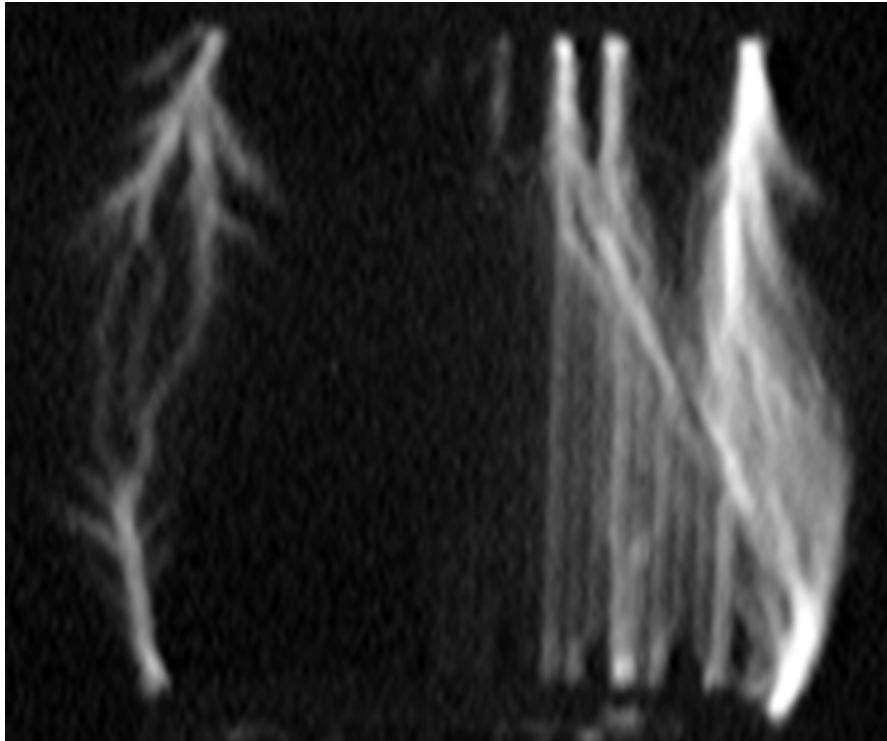
s9 5mj0002\_f1



s10 5mj0001\_f2

# Multi-Filament Tests with Substrate Masks

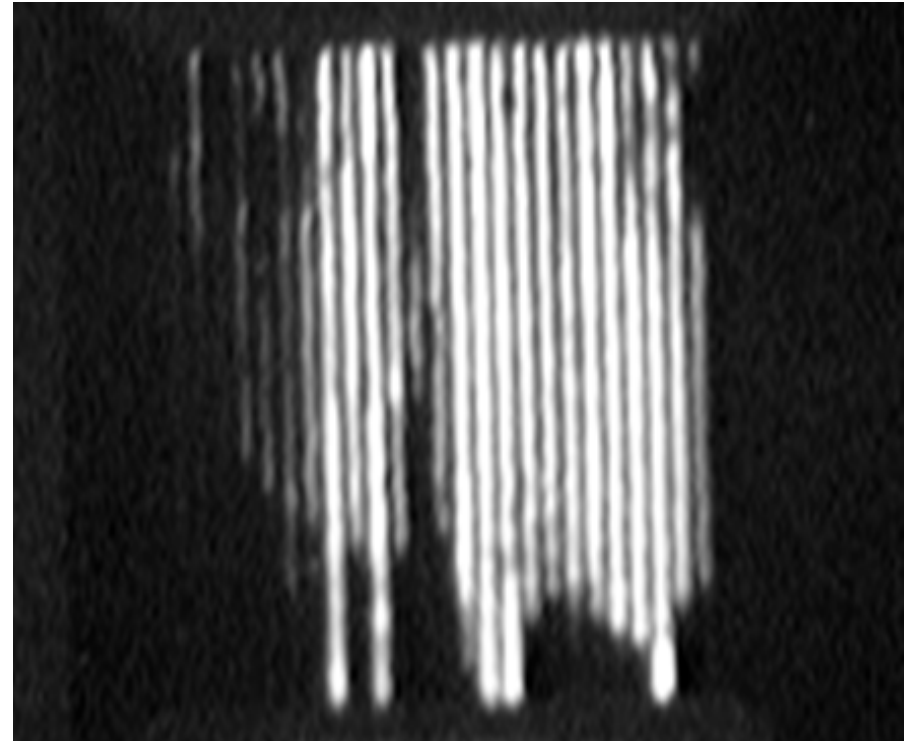
20 um stripes, 330 um spacing



S90.5 – 1.9 mJ

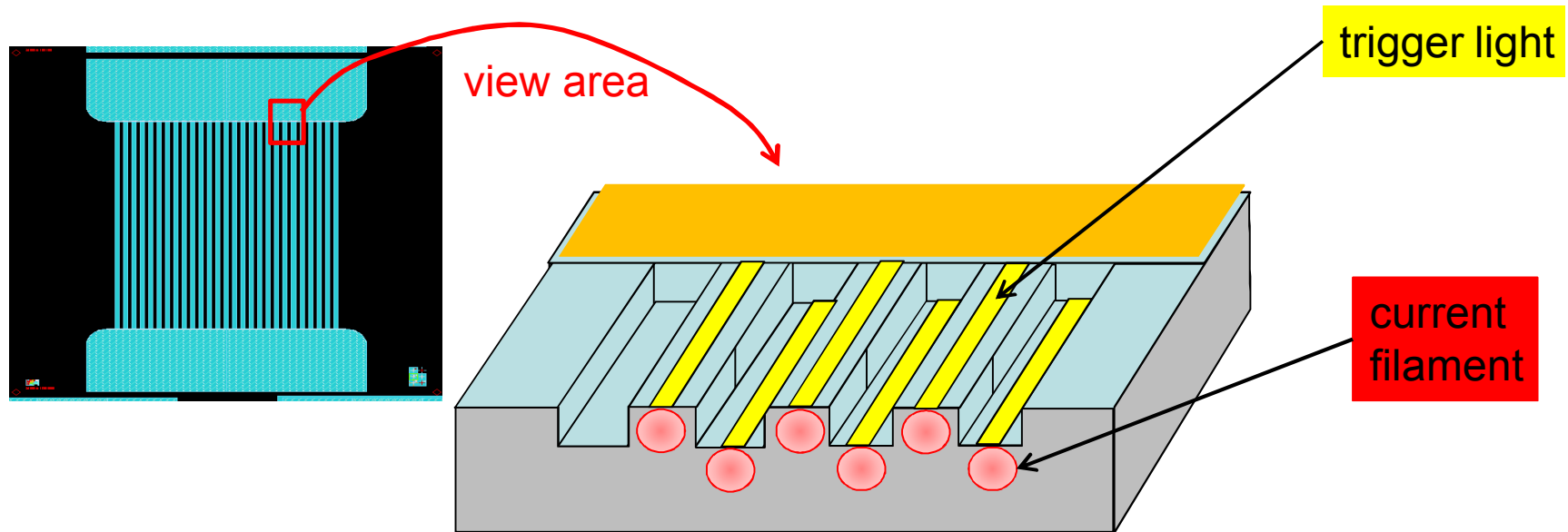
mask flaked off

80 um stripes, 330 um spacing



S28.5 – 1.5 mJ

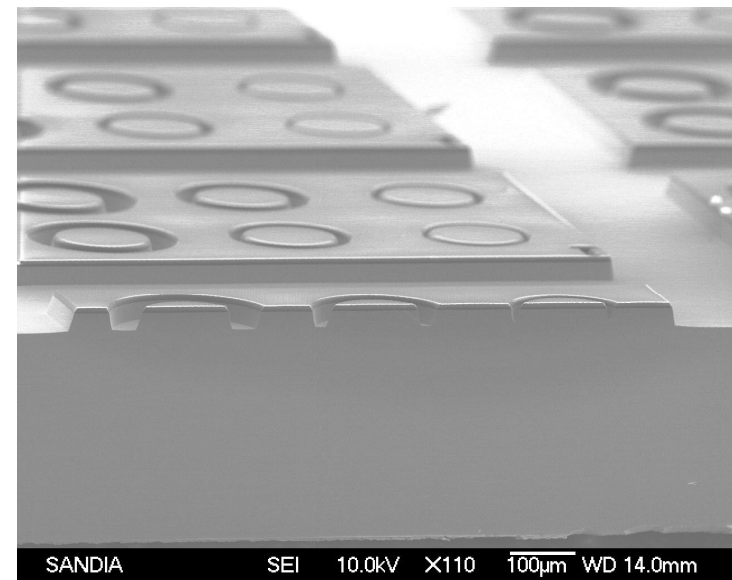
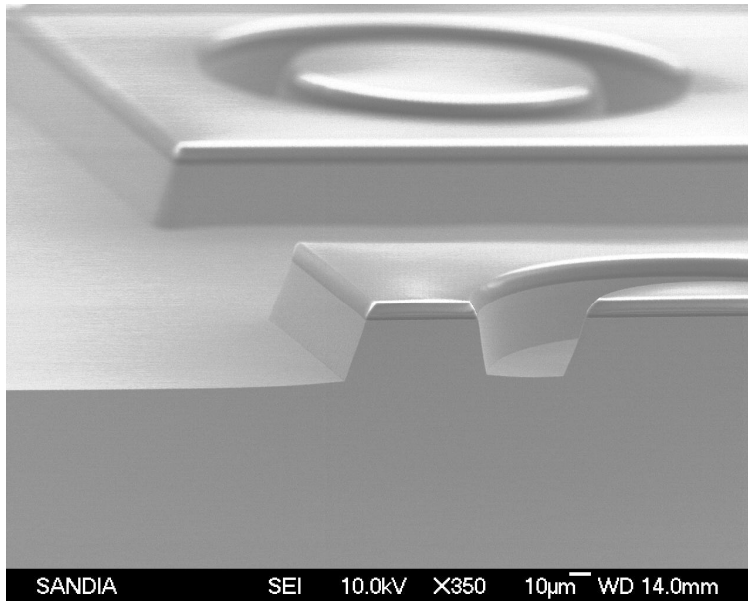
# Rib etches to control parallel filaments



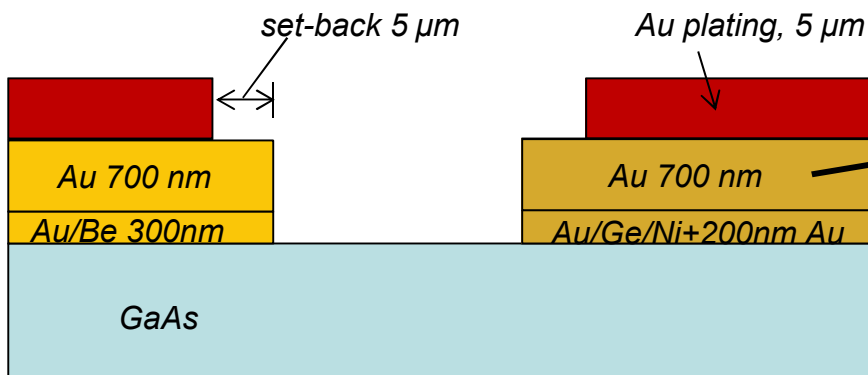
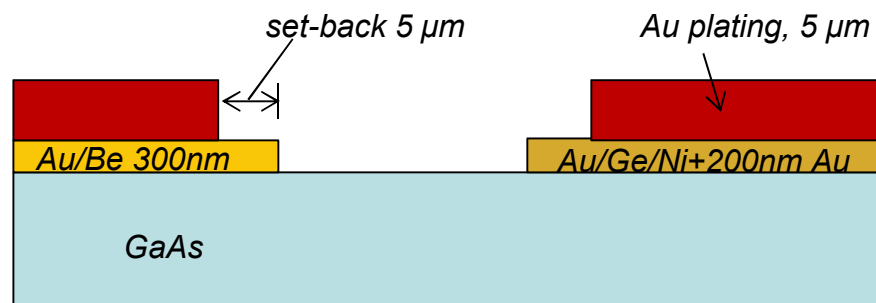
- **Light Isolation: 2 different planes**
- **Filament Isolation: vertical and horizontal distance**
- **Seed carriers determine location, branching happens early without seed carriers**
- **Experiments planned: Image trigger light on rib, on valley, or both**
- **Improve density of filaments**
- **Reduce optical trigger energy**

# GaAs filament rib etching tests

- 90 min dry etch
- ~30  $\mu\text{m}$  etch depth
- grooves wider than 50  $\mu\text{m}$  are nearly as deep as “semi infinite” grooves



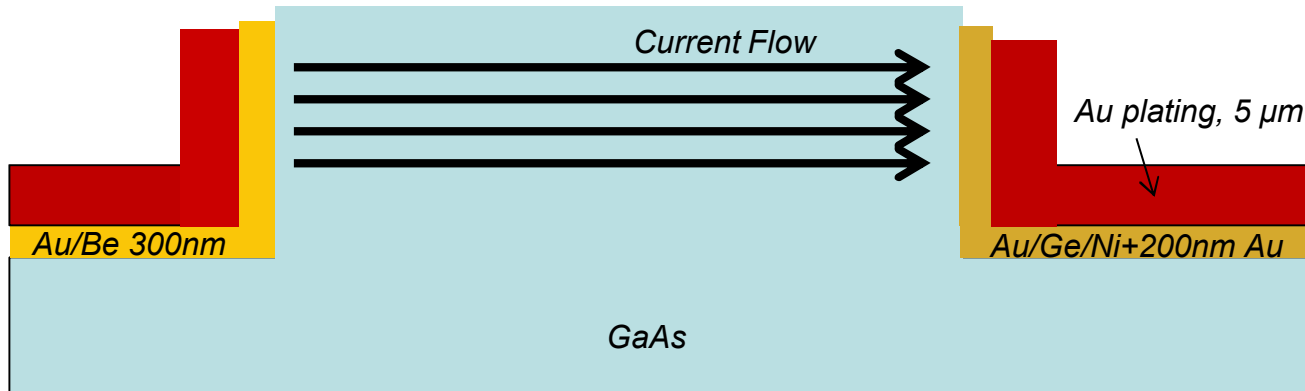
# Thick contact design



- prior HV switches were built with fairly thin metal at the edge of the contact
  - leading edge burns away with repeated shots
- **Thick contact design triples the leading edge thickness to 1 μm**
  - goal is better heat transfer away from edge and into the plated metal

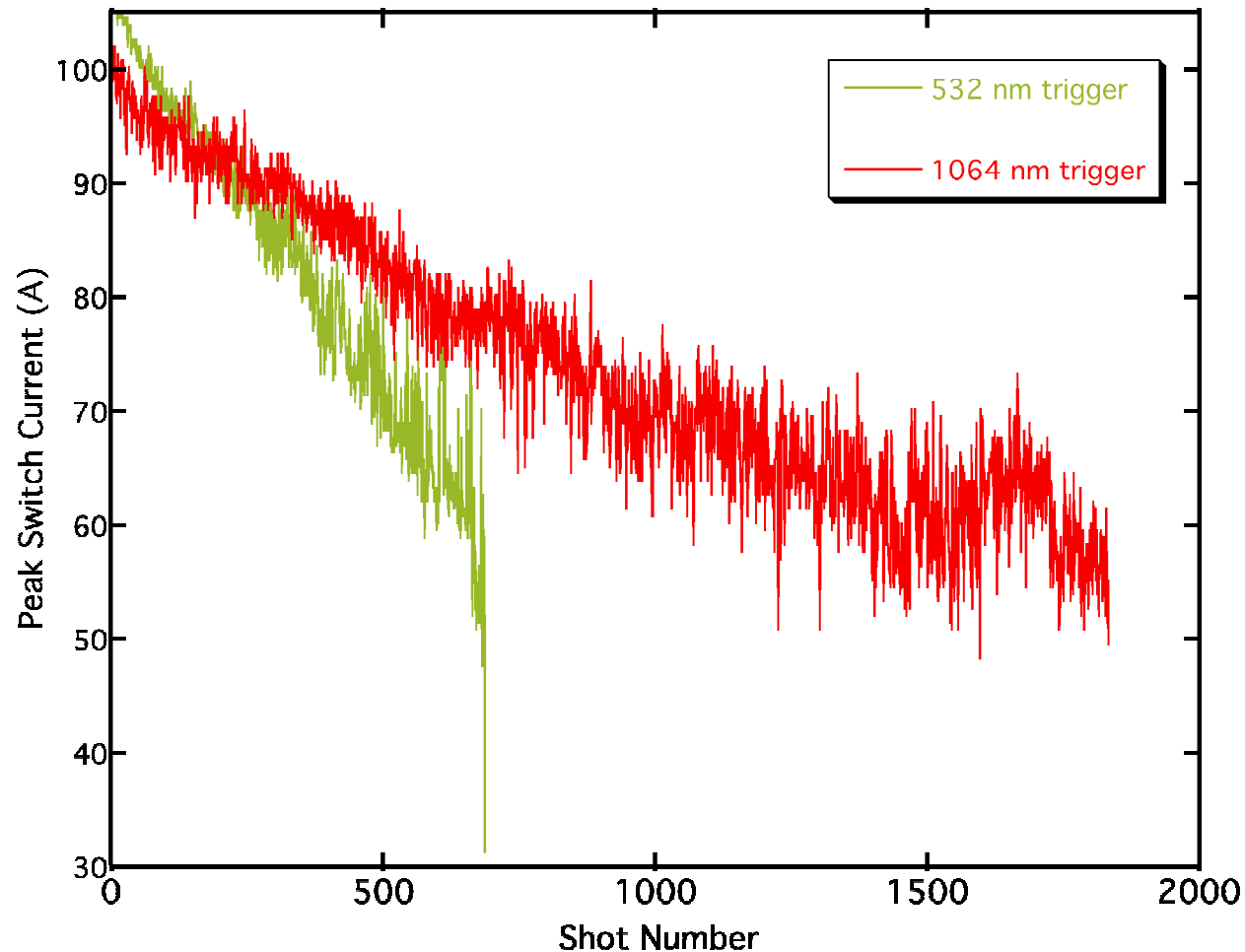


# Vertical Contact Design



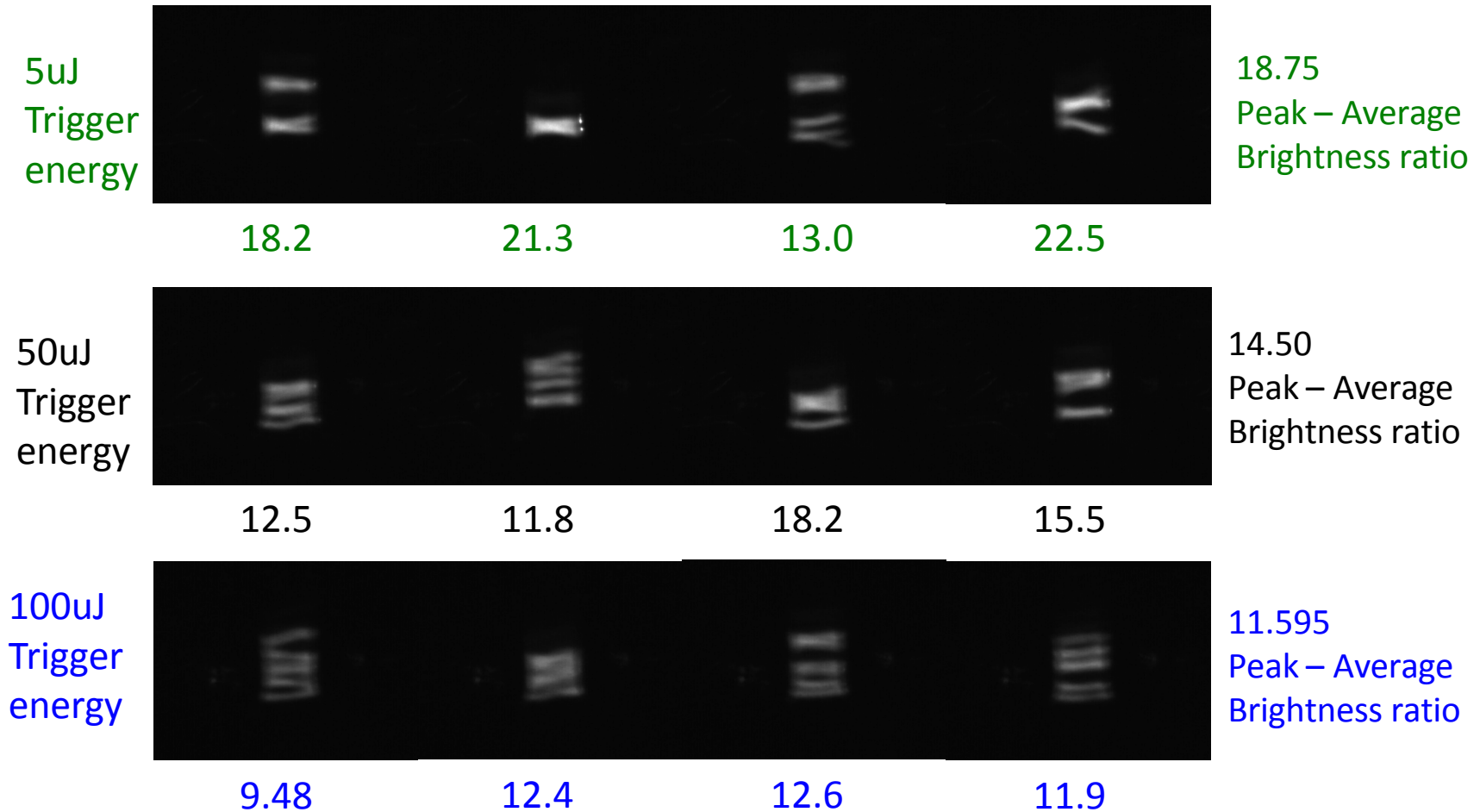
- **One ideal configuration is to terminate the filament current in a metal contact perpendicular to the E-Field**
  - Reduce current density and heating
  - Improve current handling and PCSS life

# PCSS Lifetime Dependence on Trigger Wavelength



- 532 nm strongly absorbed at the surface  
initially switches higher peak current
- 1064 nm weakly absorbed in GaAs, may initiate filaments deep in the bulk  
with lower current density for improved contact lifetime

# Filament Formation Dependence on Optical Trigger Energy

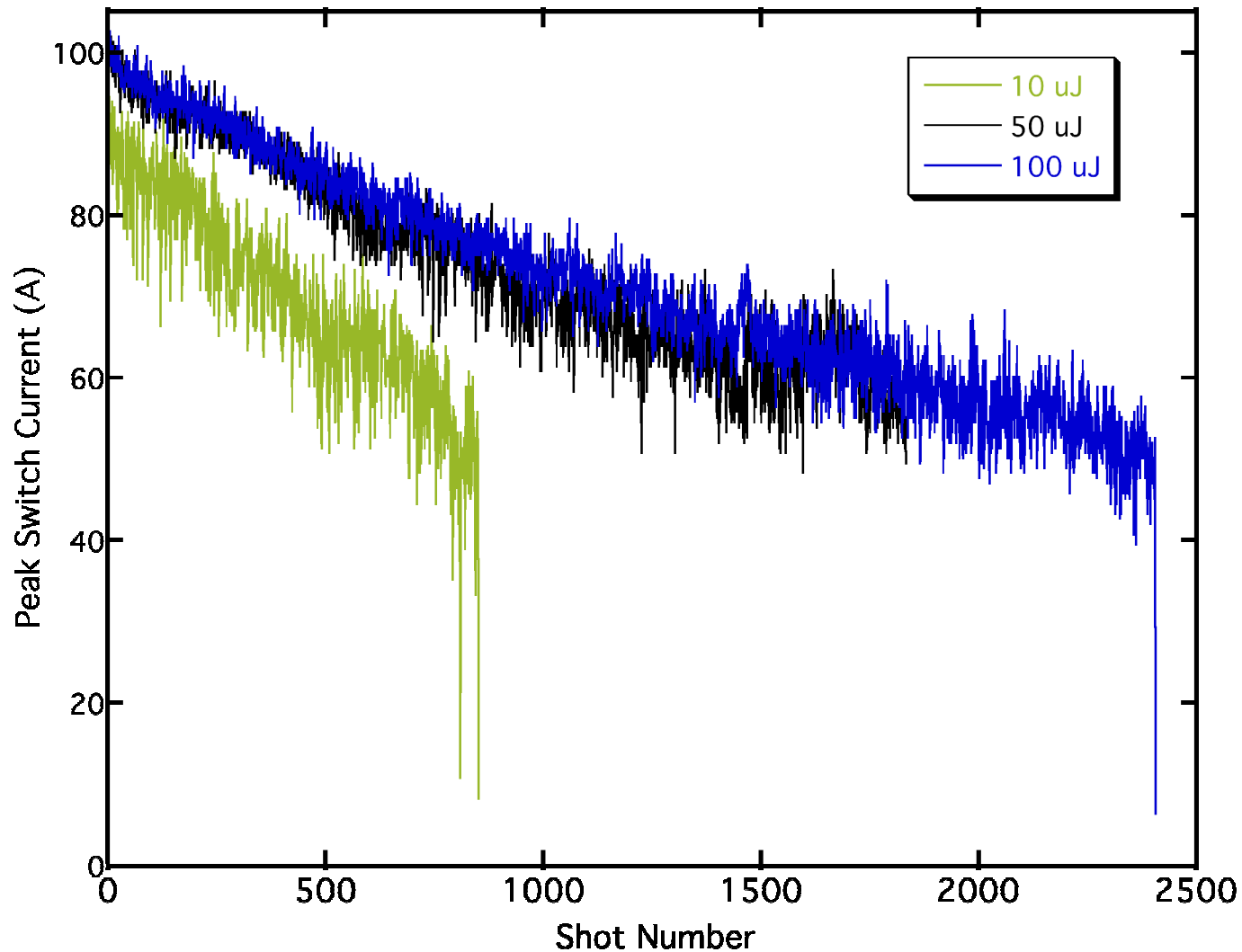


Same nominal total current for all filament images (~100A)

Higher peak brightness for filaments triggered with lower optical energy

**Higher Optical Trigger Energy Results in Reduced Peak Current Density**

# PCSS Lifetime Dependence on Trigger Energy



Reduced peak current density at higher trigger energy improves lifetime

# Conclusions

- Improving current sharing with multiple filament PCSS
- Optical trigger delivery approaches:
  1.  $\mu$ -lens arrays
  2. optical trigger masks
  3. etched ribs & valleys
- Improving contacts for more current per filament
- Testing above and below band gap triggering